

REMARKS

This is in response to the Office Action dated April 16, 2007. Claims 1-10, 13 and 14 are now pending.

Claim 1 now stands rejected under Section 103(a) as being allegedly unpatentable over Uchizaki (US 6,646,975) in view of Goltl (US 6,833,284) or Tsutsui (US 6,197,609). This Section 103(a) rejection is respectfully traversed for at least the following reasons.

Claim 1 requires that *after the substrate with the emission sources thereon is mounted on the submount*, a step of cutting *through* the substrate between the emission sources is performed to form the plurality of laser elements. For example and without limitation, Figs. 4-5 and corresponding description in the instant application illustrate that after the substrate (21) with the emission sources (14) thereon is mounted on the submount (11), a step of cutting through the substrate (21) between the emission sources (14) is performed to form the plurality of laser elements (12, 13). The cited art fails to disclose or suggest the above italicized feature of amended claim 1.

Uchizaki fails to disclose or suggest the above italicized feature of claim 1. In particular, Uchizaki fails to disclose or suggest, *after the substrate with the emission sources thereon is mounted on the submount*, cutting *through* the substrate between the emission sources is performed to form the plurality of laser elements. In Figs. 16-19 of Uchizaki relied on by the Office Action, no cutting of GaAs substrate 210 is performed *after* the substrate 210 is mounted on submount 354. Moreover, Uchizaki also fails to disclose or suggest cutting “through” the substrate 210 at any point, thereby teaching directly away from the invention of claim 1.

Recognizing the above fundamental flaws of Uchizaki, the Office Action cites to Goltl. Goltl teaches to apply a plurality of chips to a carrier, and subsequently separate the chips after

they are on the carrier (alleged submount). The Office Action contends that it would have been obvious to have separated the lasers in Fig. 19 of Uchizaki into two different emission elements after they are attached to submount 354. However, this allegation is without merit, as there is no reason why one of ordinary skill would have ever cut the lasers in Fig. 19 of Uchizaki into two different emission elements after they are attached to submount 354. Uchizaki desires an “integrated laser array” including multiple laser elements for emitting different wavelengths (e.g., col. 23, lines 32-34; col. 4, lines 60-65; col. 5, lines 6-10). The emitting elements are integrated into a single element in Uchizaki so that layers in each one can be used for the other as well. There is no teaching in the cited art which would have led one of ordinary skill to have broken the two elements of Uchizaki up into separate elements, in conflict with the express teachings of Uchizaki that they are to be “integrated.” Goltl relates to chip manufacturing, and does not provide any teaching sufficient to ignore the express teachings of Uchizaki that the emission sources are to be “integrated.” The Section 103(a) rejection should be withdrawn for at least this reason.

Additionally, for purposes of example and without limitation, in certain example embodiments of this invention there is an object of providing a semiconductor laser device including a plurality of laser elements, in which the laser elements on a substrate are separated from one another to avoid crosstalk between them, and in which the laser elements can be accurately mounted in position. Uchizaki’s laser elements are not separated, and the reference thus lacks the technical concept of suppressing or reducing crosstalk between the laser elements.

In Goltl, a wafer (1) with recesses (7) is applied to a carrier (9) and is cut by scribing from the front side. The wafer with the carrier is then subdivided into individual chips (col. 2, lines 39-42). That is, Goltl lacks the concept of mounting the divided elements on the same

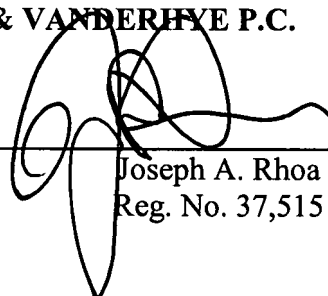
substrate with good position accuracy. There is no motivation in any of the cited art to combine Uchizaki with Goltl, as alleged in the Office Action.

It is respectfully requested that all rejections be withdrawn. All claims are in condition for allowance. If any minor matter remains to be resolved, the Examiner is invited to telephone the undersigned with regard to the same.

Respectfully submitted,

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